

KBU8005~KBU810

Rev.C Feb.-2015

描述 / Descriptions

整流桥，反向电压：50V~1000V，正向电流：8.0A，KBU 封装。

Silicon Bridge Rectifiers, Reverse Voltage:50to1000V,Forward Current:8.0A,KBU package.

特征 / Features

浪涌额定过载电流 155A，塑料材料阻燃等级 UL94-V0。

Surge overload rating -155 amperes peak,Plastic material has UL94-V0.

用途 / Applications

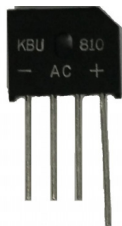
一般用途。

General purpose.

内部等效电路图 / Equivalent Circuit

见引脚排列图/ See Pinning.

引脚排列 / Pinning



印章代码 / Marking

See Marking Instructions.

极限参数 / Absolute Maximum Ratings(Ta=25°C)

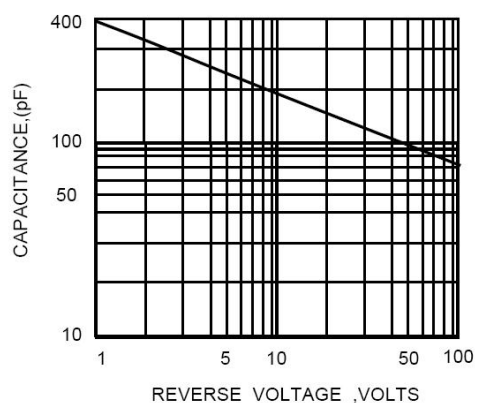
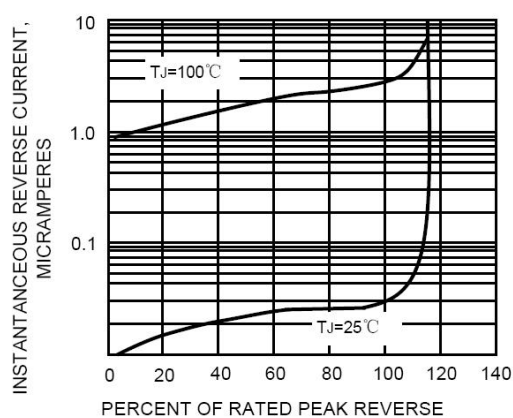
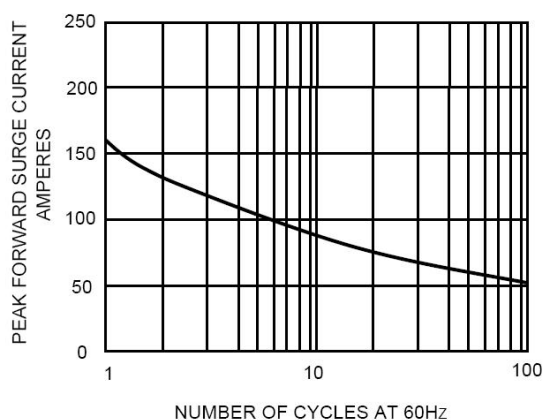
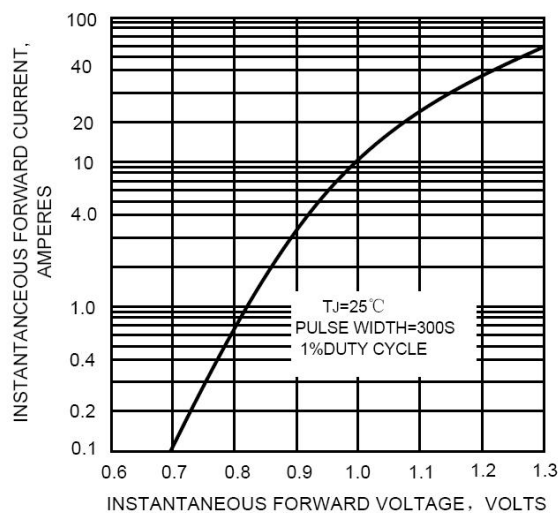
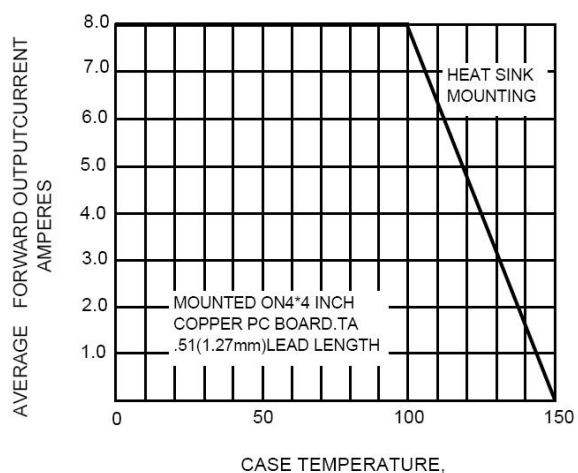
参数 Parameter	符号 Symbol	数值 Rating							单位 Unit
		KBU8005	KBU801	KBU802	KBU804	KBU806	KBU808	KBU810	
Maximum Recurrent Peak Reverse Voltage	V_{RRM}	50	100	200	400	600	800	1000	V
Maximum RMS Voltage	V_{RMS}	35	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V_{DC}	50	100	200	400	600	800	1000	V
Maximum Average Forward Rectified Output Current at $T_C=100^{\circ}C$	$I_{(AV)}$	8.0							A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load(JEDEC Method)	I_{FSM}	155							A
Typical Junction Capacitance Per Element (Note1)	C_j	250							pF
Operating Temperature Range	T_j	-55~150							$^{\circ}C$
Storage Temperature Range	T_{stg}	-55~150							$^{\circ}C$

Note:

1.Measured at 1.0MHz and applied reverse voltage of 4.0V DC.

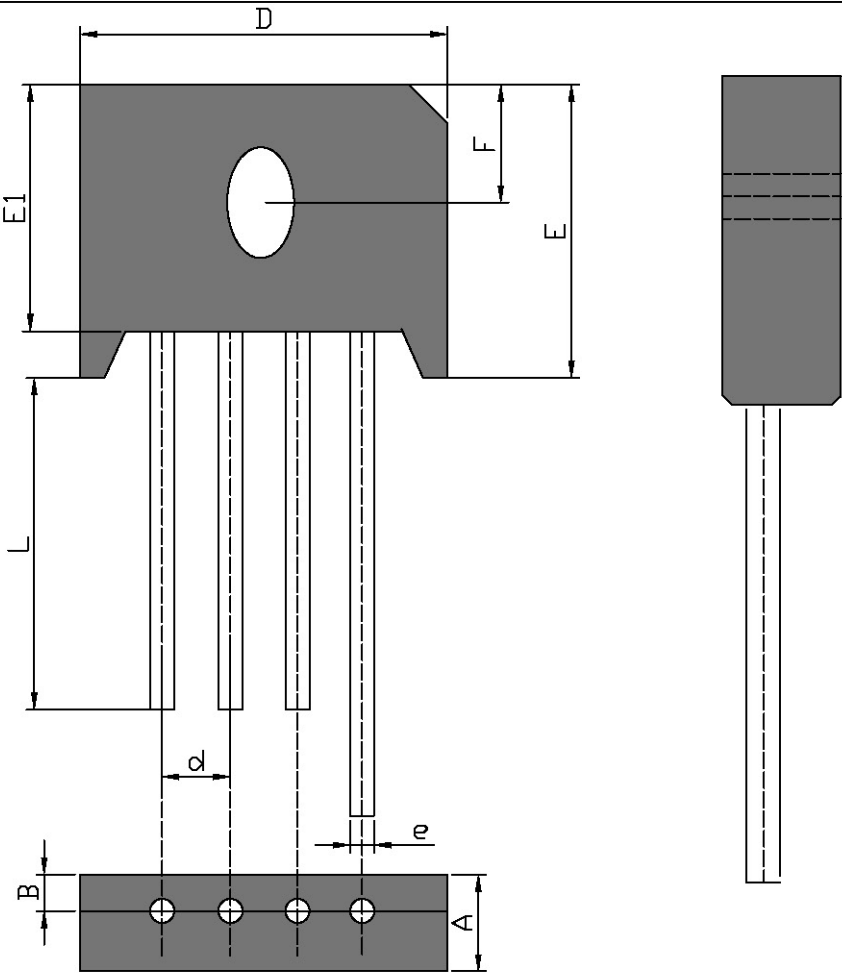
电性能参数 / Electrical Characteristics(Ta=25°C)

参数 Parameter	符号 Symbol	测试条件 Test Conditions	数值 Rating	单位 Unit
Maximum Instantaneous Forward Voltage Drop per Element	V_F	$I_F=4.0A$	1.0	V
Maximum DC Reverse Current at Maximum DC Blocking Voltage	I_R	$T_J=25^{\circ}C$	10	μA
		$T_J=100^{\circ}C$	300	μA


电参数曲线图 / Electrical Characteristic Curve


外形尺寸图 / Package Dimensions

KUB

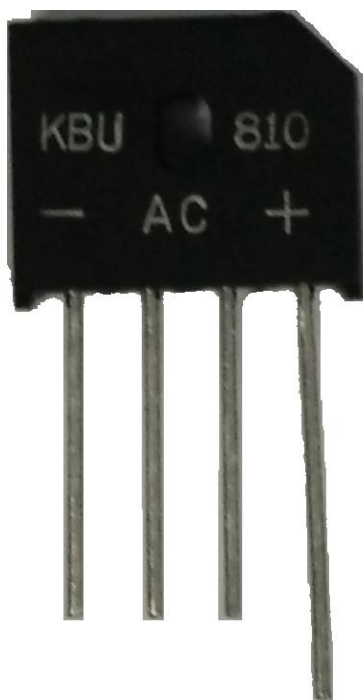


KBU mechanical data

UNIT		A	B	D	E	E1	F	L	d	e
mm	max	7.0	2.8	23.7	19.5	18.5	8.0	-	5.6	1.3
	min	6.5	2.3	22.7	18.5	17.5	7.6	19.5	4.6	1.1
mil	max	276	110	933	768	728	315	-	220	51
	min	255	90	893	728	688	299	767	181	43



印章说明 / Marking Instructions



说明：

KBU810：产品型号

- AC +：引脚功能

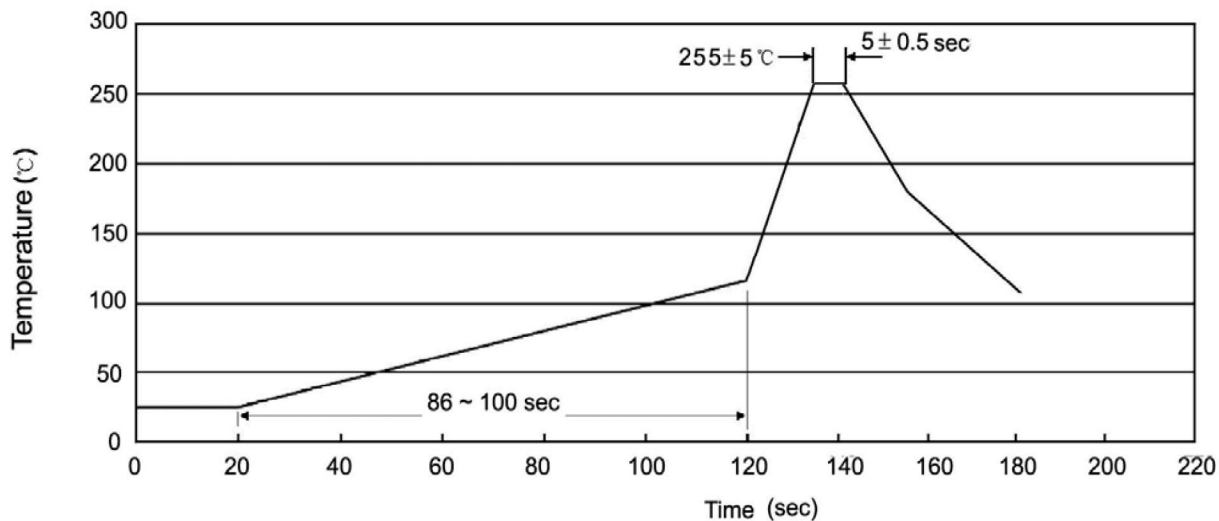
Note:

KBU810：Product Type

- AC +：Pin function



波峰焊温度曲线图(无铅) / Temperature Profile for Dip Soldering(Pb-Free)



说明：

- 1、预热温度 25 ~ 150°C，时间 60 ~ 90sec;
- 2、峰值温度 255±5°C，时间持续为 5±0.5sec;
- 3、焊接制程冷却速度为 2 ~ 10°C/sec.

Note:

- 1.Preheating:25~150°C, Time:60~90sec.
- 2.Peak Temp.:255±5°C, Duration:5±0.5sec.
3. Cooling Speed: 2~10°C/sec.

耐焊接热试验条件 / Resistance to Soldering Heat Test Conditions

温度：270±5°C

时间：10±1 sec.

Temp.:270±5°C

Time:10±1 sec

包装规格 / Packaging SPEC.

盒装包装 / BOXED

Package Type 封装形式	Units 包装数量			Dimension 包装尺寸 (unit: mm ³)		
		Units/Inner Box 只/盒	Inner Boxes/Outer Box 盒/箱	Units/Outer Box 只/箱	Inner Box 盒	Outer Box 箱
KBU		400	6	2400	230×230×49	490×240×180

使用说明 / Notices